

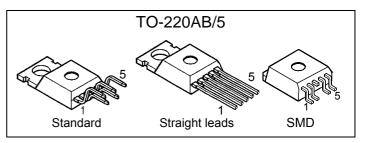
Smart Highside Power Switch

Features

- Overload protection
- Current limitation
- Short circuit protection
- Thermal shutdown
- Overvoltage protection (including load dump)
- Fast demagnetization of inductive loads
- Reverse battery protection¹)
- Undervoltage and overvoltage shutdown with auto-restart and hysteresis
- Open drain diagnostic output
- Open load detection in ON-state
- CMOS compatible input
- Loss of ground and loss of V_{bb} protection
- Electrostatic discharge (ESD) protection

Product Summary

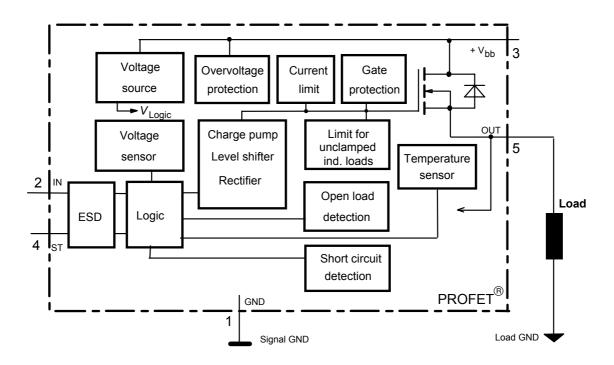
Overvoltage protection	V _{bb(AZ)}	65	V
Operating voltage	Vbb(on)	4.7 42	2 V
On-state resistance	Ron	220	mΩ
Load current (ISO)	<i>I</i> L(ISO)	1.8	Α
Current limitation	<i>I</i> L(SCr)	5	А



- Application
 μC compatible power switch with diagnostic feedback for 12 V and 24 V DC grounded loads
- All types of resistive, inductive and capacitve loads
- Replaces electromechanical relays, fuses and discrete circuits

General Description

N channel vertical power FET with charge pump, ground referenced CMOS compatible input and diagnostic feedback, monolithically integrated in Smart SIPMOS[®] technology. Providing embedded protective functions.



¹⁾ With external current limit (e.g. resistor R_{GND} =150 Ω) in GND connection, resistors in series with IN and ST connections, reverse load current limited by connected load.



Pin	Symbol		Function
1	GND	-	Logic ground
2	IN	Ι	Input, activates the power switch in case of logical high signal
3	Vbb	+	Positive power supply voltage, the tab is shorted to this pin
4	ST	S	Diagnostic feedback, low on failure
5	OUT (Load, L)	0	Output to the load

Maximum Ratings at $T_j = 25$ °C unless otherwise specified

Parameter	Symbol	Values	Unit
Supply voltage (overvoltage protection see page 3)	V _{bb}	65	V
Load dump protection ²⁾ $V_{\text{LoadDump}} = U_A + V_s$, $U_A = 13.5 \text{ V}$ $R_{\text{I}^{3)}} = 2 \Omega$, $R_{\text{L}} = 6.6 \Omega$, $t_{\text{d}} = 400 \text{ ms}$, IN= low or high	V _{Load dump} ⁴⁾	100	V
Load current (Short circuit current, see page 4)	IL.	self-limited	Α
Operating temperature range	Tj	-40+150	°C
Storage temperature range	T _{stg}	-55+150	
Power dissipation (DC), $T_C \le 25 \text{ °C}$	P _{tot}	50	W
Inductive load switch-off energy dissipation, single pulse $V_{bb} = 12V$, $T_{j,start} = 150^{\circ}$ C, $T_{C} = 150^{\circ}$ C const. $I_{l} = 1.8 \text{ A}$, $Z_{l} = 2.3 \text{ H}$, 0 Ω :	E _{AS}	4.5	J
Electrostatic discharge capability (ESD) IN: (Human Body Model) all other pins: acc. MIL-STD883D, method 3015.7 and ESD assn. std. S5.1-1993	V _{ESD}	1 2	kV
Input voltage (DC)	V _{IN}	-0.5 +6	V
Current through input pin (DC)	I _{IN}	±5.0	mA
Current through status pin (DC)	I _{ST}	±5.0	
see internal circuit diagrams page 6			

Thermal Characteristics

Parameter and Condition	Symbol		Values	;	Unit	
			min	typ	max	
Thermal resistance	chip - case:	<i>R</i> _{thJC}			2.5	K/W
jun	<i>R</i> thJA			75		
SMD v	ersion, device on PCB ⁵⁾ :			35		

²⁾ Supply voltages higher than $V_{bb(AZ)}$ require an external current limit for the GND and status pins, e.g. with a 150 Ω resistor in the GND connection and a 15 k Ω resistor in series with the status pin. A resistor for the protection of the input is integrated.

³⁾ $R_{\rm I}$ = internal resistance of the load dump test pulse generator

⁴⁾ $V_{\text{Load dump}}$ is setup without the DUT connected to the generator per ISO 7637-1 and DIN 40839

⁵⁾ Device on 50mm*50mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70µm thick) copper area for V_{bb} connection. PCB is vertical without blown air.



Electrical Characteristics

Parameter and Conditions	Symbol		Values		Unit
at $T_j = 25 \text{ °C}$, $V_{bb} = 12 \text{ V}$ unless otherwise specified		min	typ	max	

Load Switching Capabilities and Characteristics

On-state resistance (pin 3 to 5)						
<i>I</i> _L = 1.6 A	<i>T</i> j=25 °C:	R _{ON}		190	220	mΩ
	<i>T</i> j=150 °C:			390	440	
Nominal load current, ISO Norm $V_{ON} = 0.5 \text{ V}, T_{C} = 85 \text{ °C}$	I _{L(ISO)}	1.6	1.8		А	
Output current (pin 5) while GND		I _{L(GNDhigh)}			1	mA
GND pulled up, <i>V</i> _{bb} =30 V, <i>V</i> _{IN} = page 7, <i>T</i> _j =-40+150°C						
Turn-on time IN	」 to 90% <i>V</i> _{OUT} :	<i>t</i> on	12		125	μs
Turn-off time IN	└ to 10% <i>V</i> _{OUT} :	<i>t</i> off	5		85	
<i>R</i> _L = 12 Ω, <i>T</i> _j =-40+150°C						
Slew rate on		dV/dt _{on}			3	V/µs
10 to 30% V_{OUT} , $R_{L} = 12 \Omega$, $T_{j} = -$	-40+150°C					
Slew rate off 70 to 40% V_{OUT} , $R_{L} = 12 \Omega$, $T_{j} = -12 \Omega$	-40+150°C	-dV/dt _{off}			6	V/µs

Operating Parameters

Operating voltage ⁶⁾	<i>T</i> _j =-40+150°C:	V _{bb(on)}	4.7		42	V
Undervoltage shutdown	ndervoltage shutdown $T_{j} = 25^{\circ}C$:		2.9		4.5	V
	<i>T</i> _j =-40+150°C:		2.7		4.7	
Undervoltage restart	<i>T</i> _j =-40+150°C:	V _{bb(u rst)}			4.9	V
Undervoltage restart of charge see diagram page 13	V _{bb(ucp)}		5.6	6.0	V	
Undervoltage hysteresis $\Delta V_{bb(under)} = V_{bb(u rst)} - V_{bb(under)}$		$\Delta V_{ m bb(under)}$		0.1		V
Overvoltage shutdown	<i>T</i> j =-40+150°C:	V _{bb(over)}	42		52	V
Overvoltage restart	<i>T</i> _j =-40+150°C:	V _{bb(o rst)}	40			V
Overvoltage hysteresis	<i>T</i> _j =-40+150°C:	$\Delta V_{\rm bb(over)}$		0.1		V
Overvoltage protection ⁷⁾	$T_{j} = -40+150^{\circ}C:$	V _{bb(AZ)}	65	70		V
l₀b=4 mA						
Standby current (pin 3)	<i>T</i> _j =-40+25°C:	I _{bb(off)}		10	15	μA
V _{IN} =0	<i>T</i> _j = 150°C:			18	25	
Leakage output current (include Vin=0	I _{L(off)}			20	μA	
Operating current (Pin 1) ⁸⁾ , $V_{IN}=$ $T_j = -40+150^{\circ}C$	I _{GND}		1	2.1	mA	

6) At supply voltage increase up to V_{bb} = 5.6 V typ without charge pump, $V_{OUT} \approx V_{bb}$ - 2 V

⁷⁾ Meassured without load. See also V_{ON(CL)} in table of protection functions and circuit diagram page 7.



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Parameter and Conditions	Symbol		Values		Unit
at $T_j = 25 \text{ °C}$, $V_{bb} = 12 \text{ V}$ unless otherwise specified		min	typ	max	
Protection Functions ⁹⁾					
Initial peak short circuit current limit (pin 3 to 5) ¹⁰), (max 450 μ s if $V_{ON} > V_{ON(SC)}$)	I _{L(SCp)}				
$T_{j} = -40^{\circ}C:$ $T_{j} = 25^{\circ}C:$ $T_{j} = +150^{\circ}C:$		9 4	 12 	23 15	A
Repetitive overload shutdown current limit	I _{L(SCr)}				
V_{ON} = 8 V, $T_j = T_{jt}$ (see timing diagrams, page 11)			5		А
Short circuit shutdown delay after input pos. slope $V_{\text{ON}} > V_{\text{ON}(\text{SC})}$, $T_j = -40+150^{\circ}\text{C}$:	t _{d(SC)}			450	μs
min value valid only, if input "low" time exceeds 60 μs					
Output clamp (inductive load switch off) at $V_{OUT} = V_{bb} - V_{ON(CL)}$ $I_L = 40$ mA, $T_j = -40+150$ °C:	V _{ON(CL)}	61	68	73	V
<i>I</i> _L = 1 A, <i>T</i> _j =-40+150°C:				75	
Short circuit shutdown detection voltage (pin 3 to 5)	V _{ON(SC)}		8.5		V
Thermal overload trip temperature	T _{jt}	150			°C
Thermal hysteresis	ΔT_{jt}		10		K
Reverse battery (pin 3 to 1) ¹¹⁾	-V _{bb}			32	V

Diagnostic Characteristics

Open load detection current		I _{L (OL)}			mA
(on-condition)	<i>T</i> j=-40150°C:		2	 150	

- ⁸⁾ Add I_{ST} , if $I_{ST} > 0$, add I_{IN} , if $V_{IN} > 5.5$ V
- ⁹⁾ Integrated protection functions are designed to prevent IC destruction under fault conditions described in the data sheet. Fault conditions are considered as "outside" normal operating range. Protection functions are not designed for continuous repetitive operation.
- ¹⁰⁾ Short circuit current limit for max. duration of $t_{d(SC) max}$ =450 µs, prior to shutdown
- ¹¹⁾ Requires 150 Ω resistor in GND connection. The reverse load current through the intrinsic drain-source diode has to be limited by the connected load. Note that the power dissipation is higher compared to normal operating conditions due to the voltage drop across the intrinsic drain-source diode. The temperature protection is not active during reverse current operation! Input and Status currents have to be limited (see max. ratings page 2 and circuit page 7).



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Parameter and Conditions	Symbol	Values			Unit
at $T_j = 25 \text{ °C}$, $V_{bb} = 12 \text{ V}$ unless otherwise specified		min	typ	max	

Input and Status Feedback¹²⁾

Input turn-on threshold voltage $\int T_j = -40+150$ °C:	V _{IN(T+)}	1.5		2.4	V
Input turn-off threshold voltage $\sum T_j$ =-40+150°C:	V _{IN(T-)}	1.0			V
Input threshold hysteresis	$\Delta V_{\rm IN(T)}$		0.5		V
Off state input current (pin 2), $V_{IN} = 0.4 V$	I _{IN(off)}	1		30	μA
On state input current (pin 2), $V_{IN} = 5 V$	I _{IN(on)}	10	25	70	μA
Status invalid after positive input slope	$t_{\rm d(ST\ SC)}$			450	μs
(short circuit) $T_{j}=-40 \dots +150^{\circ}C$:					
Status invalid after positive input slope	<i>t</i> _{d(ST)}	300		1400	μs
(open load)					
Status output (open drain)					
Zener limit voltage $T_j = -40+150^{\circ}C$, $I_{ST} = +50 \text{ uA}$:	$V_{\rm ST(high)}$	5.0	6		V
ST low voltage $T_j = -40+150^{\circ}C$, $I_{ST} = +1.6$ mA:	V _{ST(low)}			0.4	

 $^{^{\}rm 12)}\,$ If a ground resistor $\rm R_{GND}$ is used, add the voltage drop across this resistor.



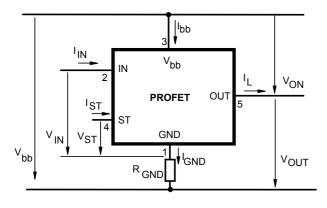


Truth Table

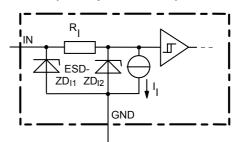
	Input-	Output		Status			
	level	level	412 B2	410 D2	410 E2/ F2	410 G2	410 H2
Normal	L	L	Н	Н	Н	Н	Н
operation	Н	Н	Н	Н	Н	Н	Н
Open load	L	13)	L	Н	н	Н	L
	н	н	Н	L	L	L	Н
Short circuit	L	L	Н	Н	Н	Н	Н
to GND	н	L	L	L	L	Н	L
Short circuit	L	Н	L	Н	Н	Н	L
to V _{bb}	н	н	Н	H (L ¹⁴⁾)	H (L ¹⁴⁾)	H (L ¹⁴⁾)	Н
Overtem-	L	L	L	L	L	L	L
perature	Н	L	L	L	L	L	L
Under-	L	L	L ¹⁵⁾	L ¹⁵⁾	Н	Н	Н
voltage	Н	L	L ¹⁵⁾	L ¹⁵⁾	н	Н	Н
Overvoltage	L	L	L	L	Н	Н	Н
_	н	L	L	L	Н	Н	Н

L = "Low" Level H = "High" Level X = don't care Z = high impedance, potential depends on external circuit Status signal after the time delay shown in the diagrams (see fig 5. page 12...13)

Terms



Input circuit (ESD protection)



 ZD_{I1} 6 V typ., ESD zener diodes are not to be used as voltage clamp at DC conditions. Operation in this mode may result in a drift of the zener voltage (increase of up to 1 V).

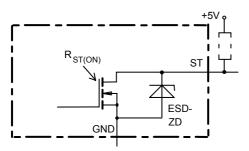
- ¹⁴⁾ Low resistance short V_{bb} to output may be detected in ON-state by the no-load-detection
- ¹⁵⁾ No current sink capability during undervoltage shutdown

¹³⁾ Power Transistor off, high impedance, versions BTS 410H, BTS 412B: internal pull up current source for open load detection.



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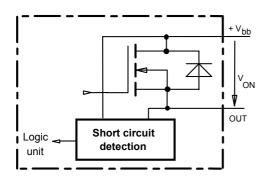
Status output



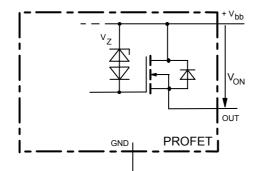
ESD-Zener diode: 6 V typ., max 5 mA; $R_{ST(ON)} < 250 \ \Omega$ at 1.6 mA, ESD zener diodes are not to be used as voltage clamp at DC conditions. Operation in this mode may result in a drift of the zener voltage (increase of up to 1 V).

Short circuit detection

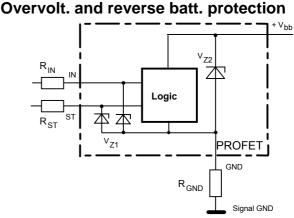
Fault Condition: $V_{ON} > 8.5$ V typ.; IN high



Inductive and overvoltage output clamp



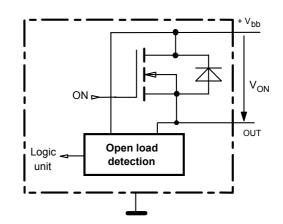
VON clamped to 68 V typ.



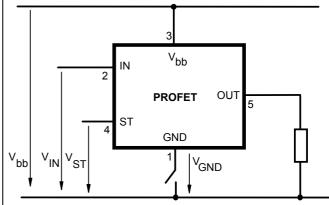
 V_{Z1} = 6.2 V typ., V_{Z2} = 70 V typ., R_{GND} = 150 Ω , R_{IN}, R_{ST} = 15 k Ω

Open-load detection

ON-state diagnostic condition: $V_{ON} < R_{ON} * I_{L(OL)}$; IN high



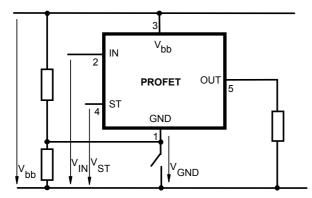
GND disconnect



Any kind of load. In case of Input=high is $V_{OUT} \approx V_{IN} - V_{IN(T+)}$. Due to V_{GND} >0, no V_{ST} = low signal available.

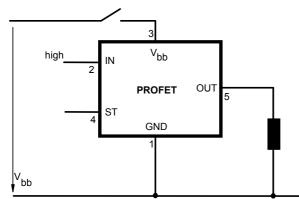


GND disconnect with GND pull up



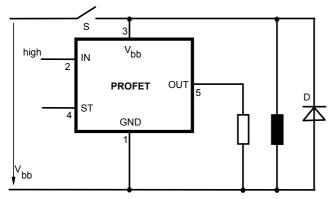
Any kind of load. If V_{GND} - V_{IN} - $V_{IN(T+)}$ device stays off Due to V_{GND} >0, no V_{ST} = low signal available.

$V_{bb}\xspace$ disconnect with energized inductive load



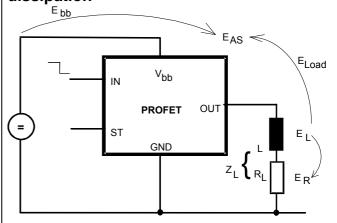
Normal load current can be handled by the PROFET itself.

V_{bb} disconnect with charged external inductive load



If other external inductive loads L are connected to the PROFET, additional elements like D are necessary.

Inductive Load switch-off energy dissipation



Energy stored in load inductance:

$$E_{\rm L} = \frac{1}{2} \cdot L \cdot I_{\rm L}^2$$

While demagnetizing load inductance, the energy dissipated in PROFET is

$$E_{AS} = E_{bb} + E_L - E_R = V_{ON(CL)} \cdot i_L(t) dt,$$

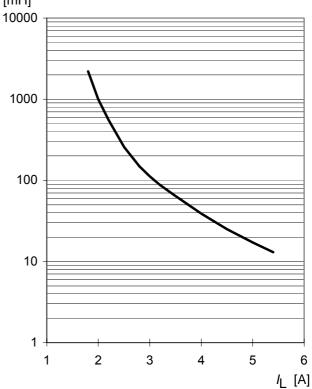
with an approximate solution for $R_L > 0 \Omega$:

$$E_{\text{AS}} = \frac{I_{\text{L}} \cdot L}{2 \cdot R_{\text{L}}} \cdot (V_{\text{bb}} + |V_{\text{OUT}(\text{CL})}|) \cdot \ln (1 + \frac{I_{\text{L}} \cdot R_{\text{L}}}{|V_{\text{OUT}(\text{CL})}|})$$

Maximum allowable load inductance for a single switch off

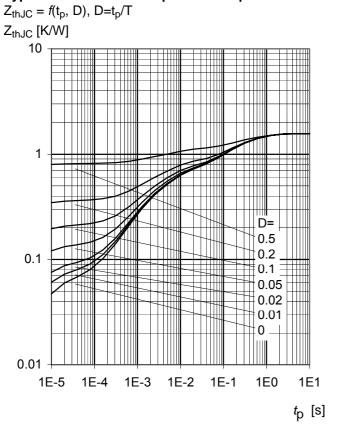
 $L = f(I_L); T_{j,start} = 150^{\circ}C, T_C = 150^{\circ}C \text{ const.},$ $V_{bb} = 12 \text{ V}, R_L = 0 \Omega$







Typ. transient thermal impedance chip case



Downloaded from Arrow.com.



Options Overview

all versions: High-side switch, Input protection, ESD protection, load dump and reverse battery protection with 150 Ω in GND connection, protection against loss of ground

greana					-			
Туре втя	412 B2	410D2	410E2	410F2	410G2	410H2	307	308
Logic version	В	D	Е	F	G	Н		
Overtemperature protection with hysteresis								
<i>T</i> _j >150 °C, latch function ¹⁶⁾¹⁷⁾	x	Х		Х		Х		Х
T_{j} >150 °C, with auto-restart on cooling			Х		Х		Х	
Short circuit to GND protection								
switches off when V_{ON} >3.5 V typ. and V_{bb} > 7 V typ ¹⁶⁾ (when first turned on after approx. 150 µs)						Х		Х
switches off when <i>V</i> _{ON} >8.5 V typ. ¹⁶⁾ (when first turned on after approx. 150 μs)	Х	Х	X	Х				
Achieved through overtemperature protection					Х		Х	
Open load detection								
in OFF-state with sensing current 30 μA typ. in ON-state with sensing voltage drop across power transistor	X	х	x	х	х	Х	Х	х
Undervoltage shutdown with auto restart	х	Х	х	Х	Х	Х	Х	Х
Overvoltage shutdown with auto restart ¹⁸	Х	Х	х	Х	Х	Х	-	х
Status feedback for								
overtemperature	x	Х	х	Х	Х	Х	Х	х
short circuit to GND	x	Х	Х	Х	-	Х	Х	Х
short to V _{bb}	Х	_19)	_19)	_19)	_19)	Х	Х	Х
open load	Х	Х	Х	Х	Х	Х	Х	Х
undervoltage	Х	Х	-	-	-	-	Х	-
overvoltage	Х	Х	-	-	-	-	-	-
Status output type								
CMOS	Х	Х						
Open drain			X	Х	Х	Х	Х	Х
Output negative voltage transient limit (fast inductive load switch off)								
to V _{bb} - V _{ON(CL)}	Х	Х	Х	Х	Х	Х	Х	Х
Load current limit								
high level (can handle loads with high inrush currents)	х	Х	Х					
low level (better protection of application)				Х	Х	Х	Х	Х
Protection against loss of GND	Х	Х	Х	Х	Х	Х	Х	Х

¹⁶⁾ Latch except when $V_{bb} - V_{OUT} < V_{ON(SC)}$ after shutdown. In most cases $V_{OUT} = 0$ V after shutdown ($V_{OUT} \neq 0$ V only if forced externally). So the device remains latched unless $V_{bb} < V_{ON(SC)}$ (see page 4). No latch between turn on and $t_{d(SC)}$.

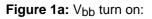
¹⁷⁾ With latch function. Reseted by a) Input low, b) Undervoltage

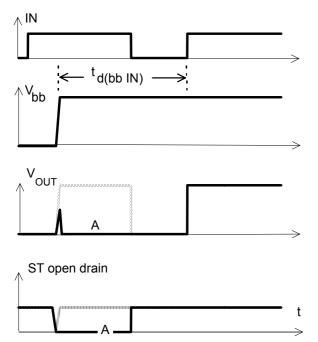
¹⁸⁾ No auto restart after overvoltage in case of short circuit

¹⁹⁾ Low resistance short V_{bb} to output may be detected in ON-state by the no-load-detection



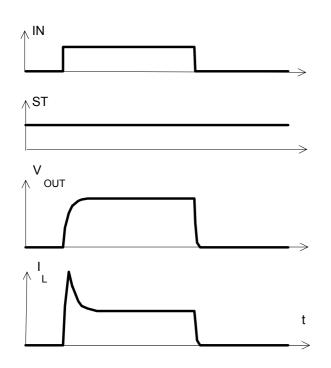
Timing diagrams

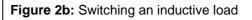


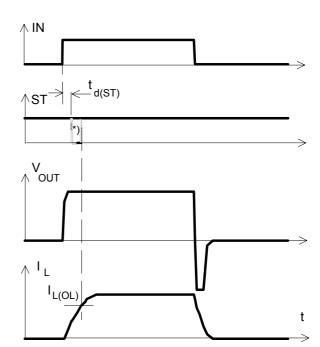


in case of too early $\textit{V}_{\text{IN}}\text{=}\text{high}$ the device may not turn on (curve A) $\textit{t}_{d(\text{bb IN})}$ approx. 150 μs

Figure 2a: Switching a lamp,

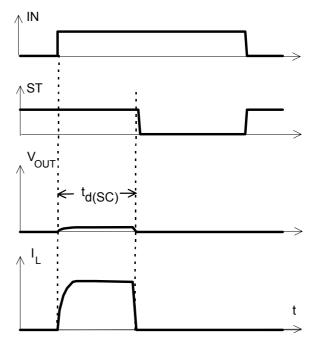






*) if the time constant of load is too large, open-load-status may occur

Figure 3a: Turn on into short circuit,



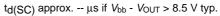
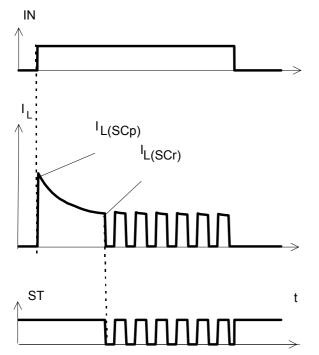
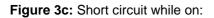


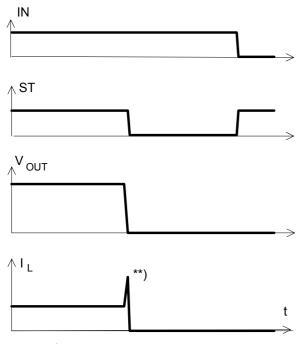


Figure 3b: Turn on into overload,



Heating up may require several seconds, V_{bb} - V_{OUT} < 8.5 V typ.





**) current peak approx. 20 µs

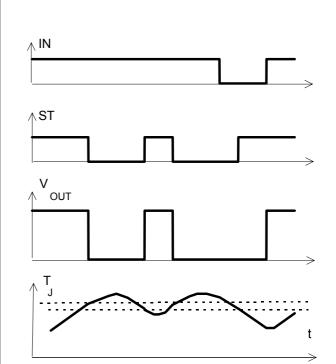
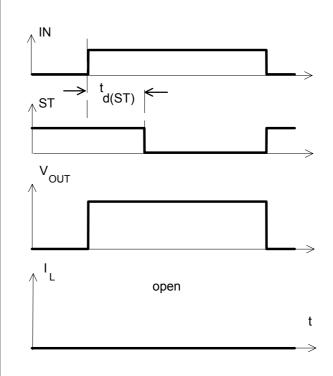


Figure 4a: Overtemperature:

Reset if $T_j < T_{jt}$

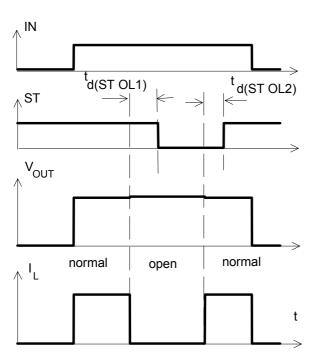
Figure 5a: Open load: detection in ON-state, turn on/off to open load





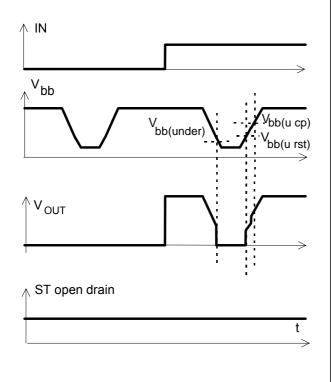
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Figure 5b: Open load: detection in ON-state, open load occurs in on-state



 $t_{d(ST OL1)} = tbd \ \mu s \ typ., \ t_{d(ST OL2)} = tbd \ \mu s \ typ$

Figure 6a: Undervoltage:



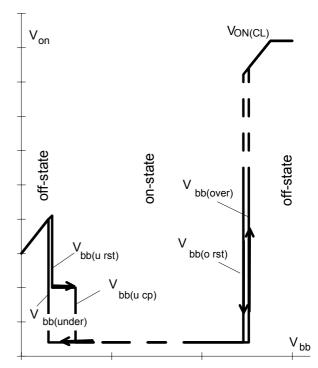


Figure 6b: Undervoltage restart of charge pump

charge pump starts at $V_{bb(ucp)} = 5.6 \text{ V typ.}$

Figure 7a: Overvoltage:

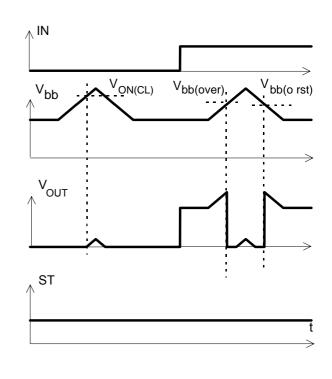
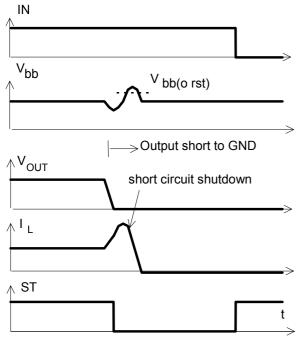


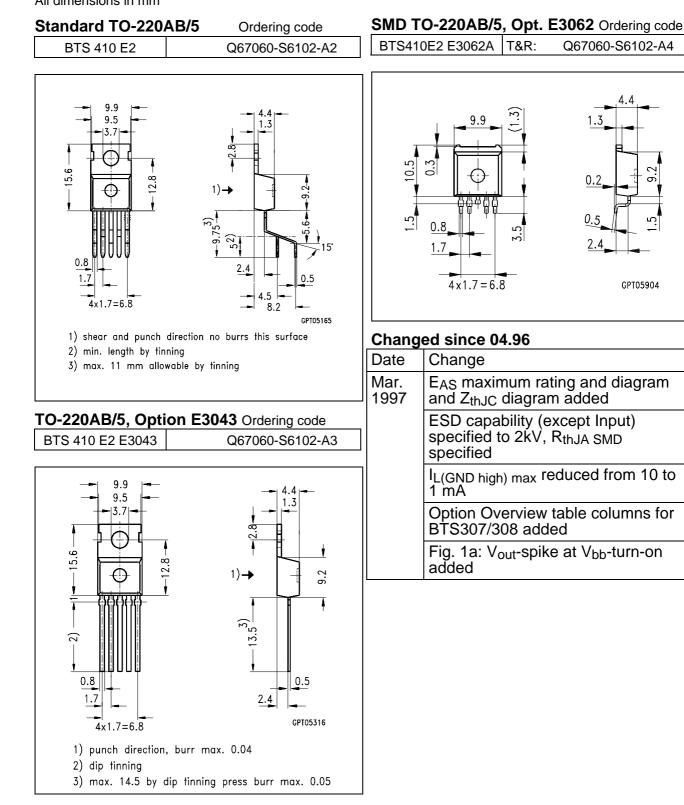


Figure 9a: Overvoltage at short circuit shutdown:



Overvoltage due to power line inductance. No overvoltage autorestart of PROFET after short circuit shutdown. Package and Ordering Code

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